Build Up HDI (Standard)

HDI08_2+4+2_1,00_35_engl

8 - Layers

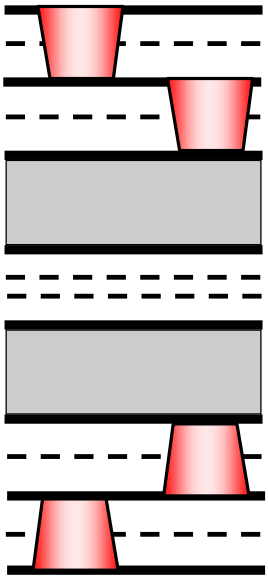
Core: 0,20 mm Cu 35/35 µm

WE-Articel No.:

2 + 4 + 2

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	**60**	
	2		Foil	12 µm		**30**	
					1 x 1080	**60**	
	3			35 µm		**33**	
			0,200 mm			**200**	
	4			35 µm		**33**	
					2 x 1080	**124**	
	5			35 µm		**33**	
			0,200 mm			**200**	
	6			35 µm		**33**	
					1 x 1080	**60**	
	7		Foil	12 µm		**30**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm	1)	12	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 980

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,00**	+/-	0,08	mm			Date: / Engineer:
thickness with electro plated Cu:	1,09	+/-	0,11	mm			
total thickness with soldermask	1,15	+/-	0,13	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision		
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	page:	10+